

Specification for TFT

AFC8001280A0-10.1INTM-I-C

Revision A



А	Orient Display			
FC	TFT Type			
8001280	Resolution 800 x 1280			
A0	Serial A0			
10.1	10.1", Module Dimension 145.5 x 231.0 x 4.86 mm			
1	IPS Display			
N	Top: -20~+70°C; Tstr: -30~+80°C			
T	Transmissive			
М	Medium Brightness, 400 cd/m2			
1	MIPI Interface			
С	Capacitive Touch Panel			
/	Controller ILI9881C Or Compatible			













Revision History

Date	Rev.	Description	Note	Page
2020-06-23	A	New issue		

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1. Features

Item	Standard Value	
Display Type	800(RGB)*1280 Dots	
LCD Type	TFT TN Normal white, Transmissive	
Screen Size(inch)	10.1	
Viewing Direction	All o'clock	
Backlight	32pcs White LED	
Weight	TBD	
Interface	MIPI	
Other(controller/driver IC)	ILI9881C	

2. Mechanical Specifications

Item	Standard Value	Unit
Outline Dimension	145.5(L)*231.0(W)*4.86(T)	mm
Active Area	135.36(L)*216.58(W)	mm
Dots Pitch	0.1692(L)*0.1692(W)	mm

3. Absolute Maximum Ratings

Item	Symbol	Condition	Min.	Max.	Unit
Analog Operating Voltage	V _{DD}	-	-0.3	7.0	V
Digital Operating Voltage	V _{DDIO}		-0.3	3.8	
Input Voltage	V _{IN}	-	-0.5	VDDI+0.3	^
HS Input Voltage	VHSIN	-	-0.3	1.65	٧
Operating Temperature	T _{OP}	-	-20	70	ů
Storage Temperature	T _{ST}	-	-30	80	°C
Humidity	-	Ta≦40°C	-	90	RH

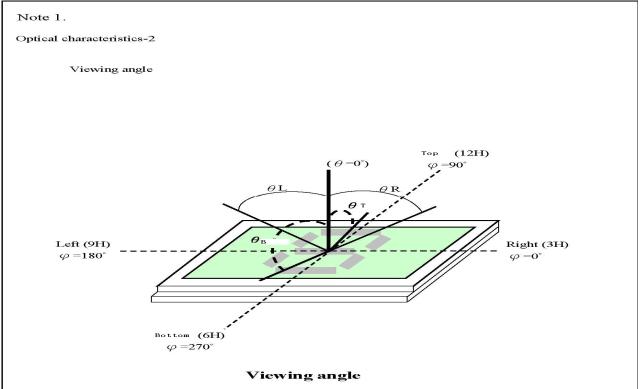
4. DC Electrical Characteristics

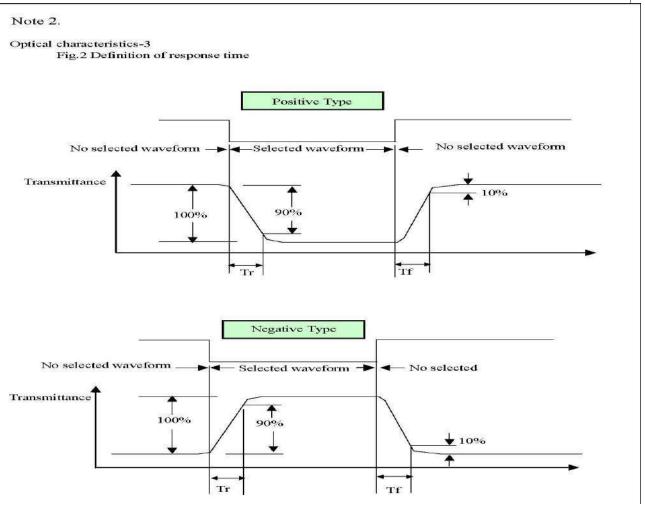
Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Analog operating Voltage	V _{ci}	Operating Voltage	2.5		6.6	V
Digital operating Voltage	V _{DDI}		1.65		3.6	V
Logic High level input Voltage	VIH		0.7*V _{DDI}		V_{DDI}	V
Logic Low level input Voltage	V _{IL}		-0.3		0.3*V _{DDI}	V
Logic High level output Voltage TE LEDPWM	V _{OH}	IOH = -1.0mA	0.8*V _{DDI}		V_{DDI}	V
"L" Output Voltage	V _{OL}	IOL = +1.0mA	0		0.2*V _{DDI}	V
Supply Current	I _{DD}	-		TBD		mA
Gate Driver High voltage	VGH			15		V
Gate Driver Low voltage	VGL			-11		V
Analog Power supply voltage	AVDD/AVEE			5/-5		V

5. Optical Characteristics

or Optical Ottalacteristics							
lte	m	Symbol	Conditions	Min.	Тур.	Max.	Reference
	Тор	ΘТ		75deg.	80deg.		
Viou Anglo	Bottom	ΘВ	C>10	75deg.	80deg.		Notes 1 & 2
View Angle	Left	ΘL	C <u>></u> 10	75deg.	80deg.		Notes 1 & 2
	Right	ΘR		75deg.	80deg.		
	White	X		0.27	0.30	0.33	
	vvriite	Y		0.29	0.32	0.35	
	Red	Х	TA=25° С Өх, ӨҮ=0°		TBD		
		Y			TBD		Notes 5
CIE *1	Green	Х			TBD		
		Y			TBD		
	Blue	Х			TBD		
		Y			TBD		
Uniformity		U	If=80mA	70%	75%		Note 4
Contrast Ratio		Cr	$\theta = \emptyset = 0^{\circ}$	800	1000		Note 3
Surface Brightness		L	∅ = 0°	400cd/m2			Note 3 & 4
Response Time (TR+ TF)		TR+TF	TA=25° C ∅ = 0°		30ms		Note 2

^{*1:} This value will be changed while mass product.





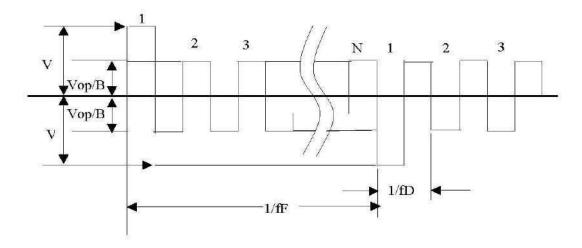
Electrical characteristics-2

※2 Drive waveform

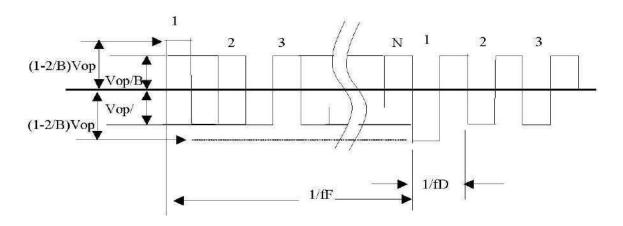
Vop: Drive voltage fF: Frame frequency 1/B: Bias fD: Drive frequency

N: Duty

(1) Selected waveform

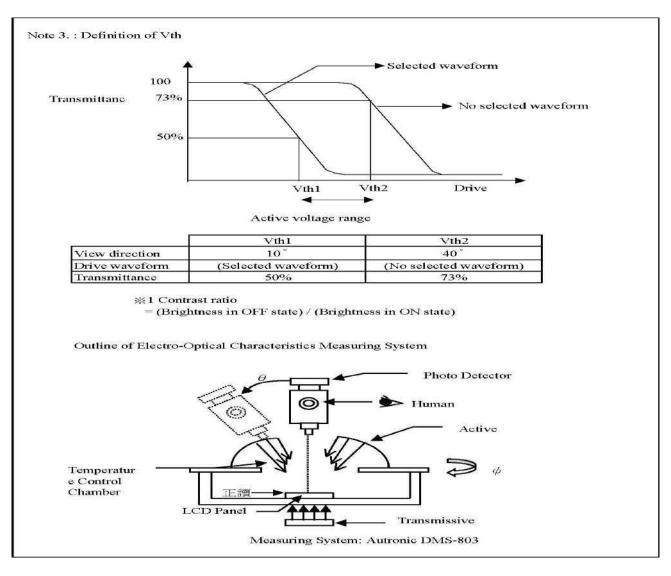


(2) Non- Selected wave form



Note:

Frame frequency is defined as follows: Common side supply voltage peak - to - peak /2 = 1 period



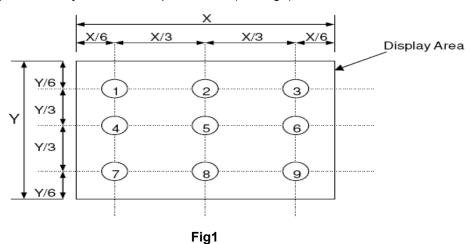
Note 4. Definition of Surface Luminance, Uniformity. (Ref Fig1)

Surface Luminance: LV=average (LP1:LP9)

Uniformity=Minimal (LP1:LP9)/Maximal (LP1:LP9)*100%

Color Coordinate: The test condition is at IF current of backlight and measured on the surface of LCD module.

Note 5. CIE(x, y) chromaticity is the Center point value. (Ref Fig1)



6. Backlight Characteristics

Item	Symbol	Conditions	Min.	Тур.	Max.	Unit
Forward Voltage	V _F	If=80mA	22.4		25.6	V
Forward Current	I _F			80mA		mA

7. Touch Panel Characteristics CTP

Item	Requirement
Touch Panel Type	СТР
Touch Controller IC	GT9271
Cover Glass surface treatment	
Capacitive Touch structure	GG
Cap Touch active area	135.36*216.58mm
Number of Sensor traces X (Tx)	32
Number of Sensor traces Y (Rx)	20
Cover Lens thickness (sensor lens)	1.1
Air bonded to LCD	OCA 0.175mm
Interface	12C
IO interface power (IOVDD)	3.3V
Normal IC power (VDD)	3.3V
Finger support	

8. Interface Pin Description TFT Interface Pin Description

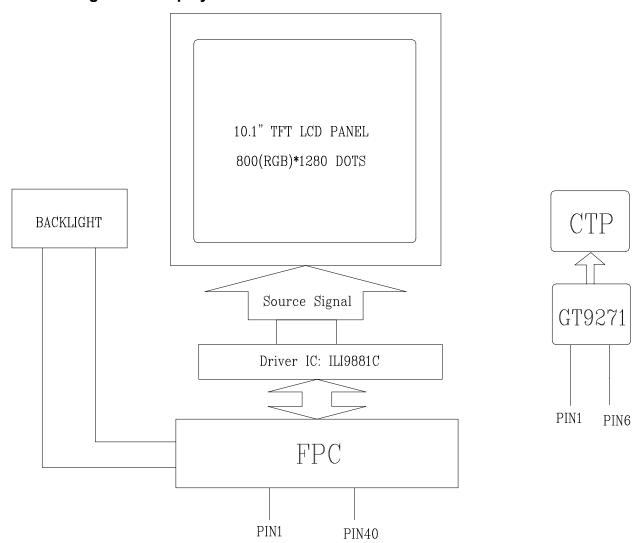
Pin No.	Symbol	Function		
1	LED+	Backlight Anode		
2	LED+	Backlight Anode		
3~8	NC	No connection		
9	LED-	Backlight Cathod		
10	LED-	Backlight Cathod		
11	GND	Ground		
12~13	NC	No connection		
14	LCD_PWM	LCD backlight control PWM output pin.		
15	LCD_ID	ID pin		
16	GND	Ground		
17~18	NC	No connection		
19	GND	Ground		
20	DSI_D3+	MIPI Data Bus		
21	DSI_D3-	MIPI Data Bus		
22	GND	Ground		
23	DSI_D2+	MIPI Data Bus		
24	DSI_D2-	MIPI Data Bus		
25	GND	Ground		

26	DSI_CLK+	MIPI Data Bus
27	DSI_CLK-	MIPI Data Bus
28	GND	Ground
29	DSI_D1+	MIPI Data Bus
30	DSI_D1-	MIPI Data Bus
31	GND	Ground
32	DSI_D0+	MIPI Data Bus
33	DSI_D0-	MIPI Data Bus
34	GND	Ground
35	NC	No connection
36	LCD_RST	LCD Reset signal.
37	GND	Ground
38	LCD_VDD	Power supply
39	LCD_VDD	Power supply
40	NC	No connection

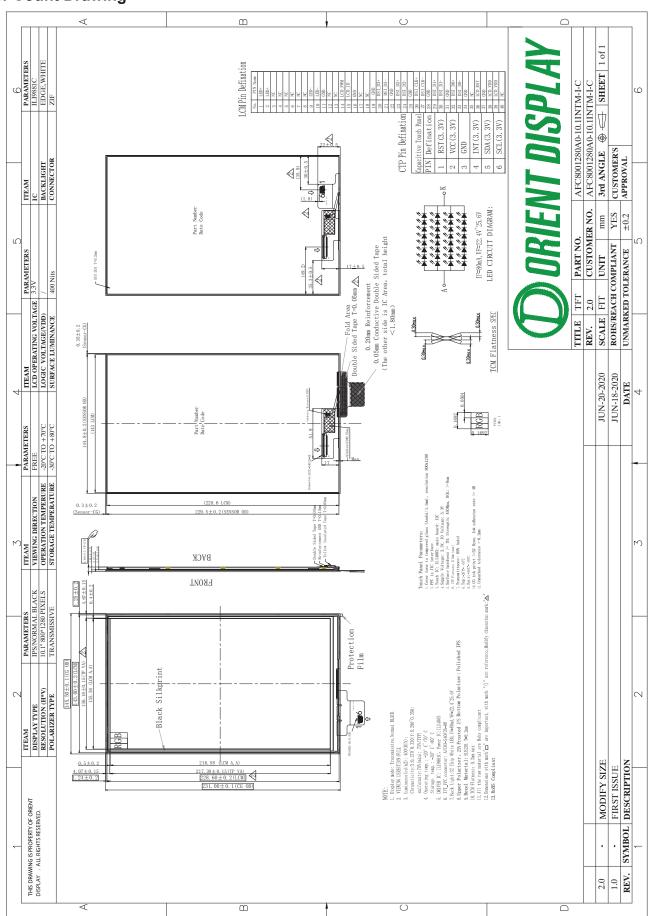
CTP Interface Pin Description

<u> </u>	The interface i in Becomption				
Pin No.	Symbol	Function			
1	SCL	CTP IIC clock			
2	SDA	CTP IIC data			
3	INT	CTP IIC data			
4	GND	Ground			
5	VCC	Power supply			
6	RST	CTP Reset signal,			

9. Block Diagram of Display



10. Count Drawing



11. Timing Characteristics

Please references ILI9881C data sheet

12. Reliability

NO	Item	Test C	Condition	
1	High Temperature Storage	Storage at 80 ± 2°C 24 hrs Surrounding temperature, then storage at normal condition 4hrs		
2	Low Temperature Storage	Storage at -30 ± 2°C 24 hrs Surrounding temperature, then storage at normal condition 4hrs		
3	High Temperature Operation	Operation at 70 ± 2°C 24 hrs		
4	Low Temperature Operation	Operation at -20 ± 2°C 24 hrs		
5	High Temperature /Humidity Operating	Operation at 60 ± 2°C, 90%RH 96 hrs surrounding temperature, then storage at normal condition 4hrs.		
6	Thermal shock (non-operation)	-30°C → 25°C → 70°C (60mins) (10mins) (60mins) 4 12 Cycle		
7	Mechanical Test	Freq.: 10-55Hz Max. Acceleration: 5G X.Y.Z. each direction For 10 mines. Drop them through		
8	ESD Test	50cm height to strike horizontal plane Air Discharge: Apply +/-8KV with 5 times Discharge for each polarity +/- 1. Temperature ambiance: 15°C~35°C 2. Humidity relative: 30%~60% 3. Energy Storage Capacitance(Cs+Cd): 150pF+/-10% 4. Discharge Resistance(Rd): 330Ω+/-10% 5. Discharge, mode of operation: Single Discharge (time between successive discharges at least 1 sec) (Tolerance if the output voltage indication: +/-5%)		

Note 1. For humidity test, DI water should be used

Inspection Standard: Inspect after 1-2hrs storage at room temperature, the sample shall be free from the following defects:

Air bubble in the LCD

Seal Leakage

Non-display

Missing Segment

Glass Crack

IDD is greater than twice initial value

Others as per QA Inspection Criteria

Note 2. No defect is allowed after testing.

Note 3. ESD should be applied to LCD glass panel, not other areas (such as on IC and so on)
IDD should be within twice initial value.

In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judged as a good part.

Note 4. Only upon request.

Note 5. ODNA carried out a high temperature and high humidity test at 60 ° C / 90% for 240 hours as an

ability measurement of this product. As a result, it was confirmed that no abnormality occurred in the product. No indication or external shape abnormality. No FPC corrosion deterioration. Please refer to the official test report on the separate sheet. This result is only for confirming the ability of these 10pcs samples, and does not guarantee the reliability can always meet the above specifications.

13. Specification of Quality Assurance

13.1 Purpose

This standard for Quality Assurance assures the quality of LCD module products supplied to customer by ODNA.

13.2 Standard for Quality Test

ODNA performs the following tests to ensure the quality of product before shipment.

Sampling Plan:

GB/T2828.1-2003. Single sampling, Normal Inspection Level II.

Single sampling, normal inspection

Sampling Level:

Minor Defect: AQL 0.65% Major Defect: AQL 0.15%.

Reliability Test:

Detailed requirement refer to Reliability Test Specification.

Nonconforming Analysis & Disposition

Nonconforming analysis

Customer should provide overall information of non-conforming sample for their complaints.

After receipt of detailed information from customer, the analysis of nonconforming parts usually should be finished in one week.

If ODNAcan not finish the analysis on time, customer will be notified with the progress status.

Disposition of nonconforming:

Non-conforming product over ppm level will be replaced.

The cause of non-conformance will be analyzed. Corrective action will be discussed and implemented.

Agreement Items

ODNA and customer shall negotiate if the following situation occurs

There is any discrepancy in standard of quality assurance.

Additional requirement to be added in product specification.

Any other special problem.

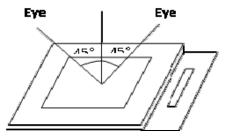
13.3 Standard of the Product Visual Inspection

Appearance inspection

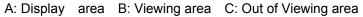
The normal inspection must be under illumination no less than 800lux, and the distance of view must be between 30cm and 45cm;

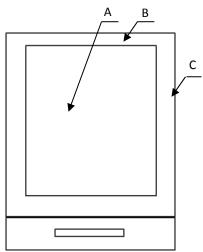
When inspect the model of transmissive product, back light must be lighted.

The visual viewing angle should be 45° from the vertical line without reflection shine or follows customer's viewing angle specifications.



Definition of area(refer to product drawing)





Basic principle:

According to IPC standards if standard is not described in specification.

A set of sample to indicate the limit of acceptable quality level must be discussed by both Casil and customer when there is any dispute happened.

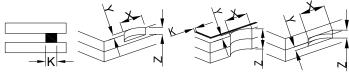
New item must be added on time when it is necessary.

13.4 Inspection Specification

No.	Item	Criteria (Unit: n	nm)					
Func	Functional							
01	LC leakage	LC leakage	Reject	Maj				
02	Non-display	Non-display	Reject	Maj				
03	Missing segment/ Missing character, dot or icon.		Reject	Maj				

04	Exceeded dot/line/segment /Distortion						Reject		Maj
05	Dim Display	part of figures disp obv	olay d iously		As th		mples co	onfirmed er	Min
06	Wrong view angle	View angle is di	fferer	nt from spec.			Reject		Maj
07	Not light	1.Backlig 2. Some L					Reject		Maj
08	Backlight Luminance \ uniformity	According to the p		•			Reject		Min
09	Backlight Color	According to the post or limited					Reject		Min
10	CTP no response	CTP touch	no re	sponse			Reject		Maj
11	Connection failure	FPC gold fi	nger o	damage	Reject		Maj		
Арре	earance			L					
01	Black and white spot, Red, blue and green spot Dent Foreign material (Round type)	φ= (a + b) /2 Distance between 2 defects should more than 10 mm apart.		A Size(mm) 0.1mm≤D≤0.2m 0.2 <d≤0.3mm 0.3<d≤0.4mm="" φ="">0.40 Total</d≤0.3mm>	nm n	Zone A 1 0	Acc. Q E Zone B 3 2 1 0 7	-	Min
02	Black and White line Scratch Foreign material (Line type) (Min)	Length (mm) $L \leq 2$ $L \leq 2$ Distance between 2	То	$\begin{array}{c} \text{Width} \\ \text{mm} \\ \text{W} \leq 0.03 \\ \text{S} < \text{W} \leq 0.05 \\ \text{W>0.50} \\ \text{tal} \end{array}$		nne		Zone C NC NC NC	Min

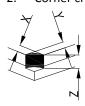
		Diameter:		Acc	ept Qty		
03	Polarizer concave	Φ(mm)	Zone A		Zone B	ZoneC	Min
	convex/bubbles	L≤0.6mm, W≤1mm	/		1	Ignore	
		Distance between 2 defe	cts sho	ould more th	an 10mm a	part.	
04	Bright/Dark dots, lines, Pixel defects	*A dot is defined as a single pixel (either red, green, or building a pixel. Definition of Bright dots: Duthat can be seen through 6% filter. Bright dots(Min) Adjacent bright dots Dark dots Adjacent dark dots Tiny bright dots Mura(50% GERY) Dark or Bright Lines Blank pixel/ Missing pixel Remark: One pixel consists of 3 dot(Sub-pixel=Dot) Note 1 Bright dot is defined through 69 TFT-LCD Panel Defects on the black Matrix, or defect counted. Symbols	olue) oots % ND sub-p	Judge by 69 with 30cm see, NG Judge by 69 with 30cm see, NG Judge by 69 with 30cm see, NG Judge by 69 with 30cm see, NG Judge by 69 with 30cm see, NG Judge by 69 with 30cm see, NG Judge by 69 with 30cm see, NG	filter as foll Eye Po 35cm ~ 40cm ND Filt	check still can check still can B lowing: osition	Min
05	TFT Glass cracked	X: Chip length Z: Chip thickness T: Glass thickness L: Electrode pad length a) General glass chip 1. Chip on panel surface	K: S A: L	Chip width Seal width .CD side leng crack betwee			Min



		· · · · · · · · · · · · · · · · · · ·
Z: Chip thickness	Y: Chip width	X: Chip length
Z ≤1/2T	Not expanded in viewing area	X≤1/8A
1/2T< Z ≤ 2Tmm	Not exceed 1/3K	X≤ 3mm

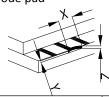
If there are 2 or more chips, X is the total length of each chip.

2. Corner crack:



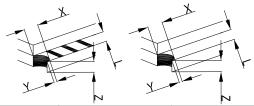
X, Y, Z Spec. same as a.1. If there are 2 or more chips, X is the total length of each chip.

- b) Protrusion over terminal:
 - 1. Chip on electrode pad



Y: Chip width	X: Chip length	Z: Chip thickness
Y≤ 1/4L	X≤ 3mm	0 <z≤t< td=""></z≤t<>

2. Non-conductive portion

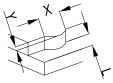


	r ·	, ,
Y: Chip width	X: C ip I ngt	Z: C ip thickness
Y≤1/3L	X≤ 3mm	0 <z≤t< td=""></z≤t<>

If the chipped area reach the ITO terminal, over 2/3 of the ITO must be remained.

If the product will be heat sealed by the customer, the alignment mark must not be damaged.

3. Substrate protuberance and internal crack



Y: Width	X: Length
Y≤1/4L	X≤A

c) LCD with extensive crack line is unacceptable.

06	Discolor/rainbow	Discolor between the LCDs or in the same LCD	Refer to the limit samples signed by customers or ODNA	Min
		Connect surface oxidation	Not allow	Maj
	07 FPC/FFC /TAB/HSC	Etching/damage /distortion	Not exceed 1/3 width of wire	Min
07		Connect surface contamination /foreign material	Width & length of electric foreign material could not exceed the witdth of 2 pins	Min
		Connect surface scratch	The scratch depth not exceed 1/2 thickness of gold layer.	Min
		Copper/protective film/base board film separate	Not allow	Maj
		Others: FPC follow IF	C-6013A standard.	
		Cold soldering, short soldering	Reject	Min
08		Not enough solder paste	Solder paste area < 75% solder pad area Solder paste area < 75% component solder point Solder paste height <1/2 component height	Min
	Soldering	FPC Pin deviation	Deviation area > 1/3 Solder pad	Min
		Others: Follow IPC	-A-610E standard	

		a) Not exceed the surface of top polarizer, LCD left/right edges. Cover				
		fully ITO, IC and the juncture of HSC/FPC and LCD.				
		b) No visible non-metal foreign material and metal material in				
		coating				
00		c) Entrapped air bubble isn't permissible to exist on the juncture				
09	COG silicon coating	of coating glue and pins of LCD.				
		d) Bubbles or pinhole of silicon coating should Φ≤2mm				
		e) The silicon should cover all around the IC and not gap in				
		between silicon and side of IC, lack of coating on top of IC can				
		be accepted				
		Symbols				
		X: Chip length Y: Chip width Z: Chip thickness				
		Chip on corner or edge				
10	CTP Cover Glass		Min			
		21				
		Z: Chip thickness Y: Chip width X: Chip length				
		Z ≤ 1/2T < 0.5mm				
		Product diagonal length Warpage range				
		(mm) (mm)				
		L≤10 0.05				
		10 <l≤30 0.1<="" td=""><td></td></l≤30>				
11	Glass warping	30 <l≤100 0.2<="" td=""><td>Maj</td></l≤100>	Maj			
		100 <l≤300 0.4<="" td=""><td></td></l≤300>				
		300 <l≤1000 0.6<="" td=""><td></td></l≤1000>				
		1000 <l≤3000 0.8<="" td=""></l≤3000>				
12	Color of silk Screen	Refer to limit sample or measurement data base on SPEC				
		1.Spots or scratches that appear when light must be judged using LCD				
13	Backlight		Min			
	_	glass spot, line and contamination standards. 2.Brightness and Chromaticity can't be out of specification.				
14	Pozal	a) No rust, distortion on the Bezel.				
14	Bezel	b) No visible fingerprints, stains or other contamination.	Min			

Dent	1 mm > Ø > 0.5 mm,	Accept	Min
	Ø≤0.5 mm	ignore	Min
Exposed base metal material on front surface	Ø≤0.5 mm ,2pcs	Accept	Min
Exposed base meta material on side	Dot: Ø≤1.0mm, Line: L≤2.0mm、 W≤0.5mm	Accept	Min
Scratched	Exposed base metal material	Reject	Min

13.5 RoHS Compliance

The product is compliant to RoHS.

14. Package Specification

TBD

15. Precaution for Using LCD Module

15.1 Handing Precaution

- 15.1.1 The display panel is made of glass and polarizer. As glass is fragile. It tends to become or chipped during handing especially on the edges. Please avoid dropping or jarring. Do not subject it to a mechanical shock by dropping it or impact.
- 15.1.2 If the display panel is damaged and the liquid crystal substance leaks out, be sure not to get any in your mouth. If the substance contacts your skin or clothes, wash it off using soap and water.
- 15.1.3 Do not apply excessive force to the display surface or the adjoining areas since this many cause the color tone to vary. Do not touch the display with bare hands, This will stain the display area and degraded insulation between terminals(some cosmetics are determined to the polarizer)
- 15.1.4 The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully. Do not touch, push or rub the exposed polarizer with anything harder than an HB pencil lead (glass, tweezers, etc.).Do not put or attach anything on the display area to avoid leaving marks on it. Condensation on the surface and contact with terminals due to cold will damage, stain or dirty the polarizer. After products are tested at low temperature they must be warmed up in a container before coming in to contact with room temperature air.
- 15.1.5 If the display surface becomes contaminated, breathe on the surface and gently wipe it whit a soft dry cloth. If it is heavily contaminated, moisten cloth with one of the following solvents,-Isotropy alcohol or Ethyl alcohol; do not scrub hard to avoid damaging the display surface.
- 15.1.6 Solvents other than those above-mentioned madly damage the polarizer. Especially, do not use the following: water, Ketone, Aromatic solvents. Wipe off saliva or water drops immediately, contact with water over a ling period of time may cause deformation or color fading. Avoid contact with oil and fats.
- 15.1.7 Exerciser care to minimize corrosion of the electrode. Corrosion of the electrodes is accelerated by water droplets, moisture condensation or current flow in a high-humidity environment.

- 15.1.8 Install the LCD module by using the mounting holes. When mounting the LCD module make sure it is free of twisting, warping and distortion. In particular, do not forcibly pull or bend the I/O cable or the backlight cable.
- 15.1.9 Do not attempt to disassemble or process the LCD module.
- 15.1.10 NC terminal should be open. Do not connect anything.
- 15.1.11 If the logic circuit power is off, do not apply the input signals.
- 15.1.12 Electro-Static Discharge control, since this module uses a CMOS LSI, the same careful attention should be paid to electrostatic discharge as for an ordinary CMOS IC. To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.
- 15.1.13 Since LCM has been assembled and adjusted with a high degree of precision, avoid applying excessive shocks to the module or making any alterations or modifications to it.

15.2 Storage Precaution

- 15.2.1 Store them in a sealed polyethylene bag. If properly sealed, there is no need for the desiccant.
- 15.2.2 Store them in a dark place. Do not expose to sunlight or fluorescent light, keep the temperature between 0°C and 35°C, and keep the relative humidity between 40% RH and 60% RH.
- 15.2.3 The polarizer surface should not come in contact with any other objects (we advise you to store them in anti-static electricity container in which they were shipped).
- 15.2.4 During shipment, please handle with care. The packaging bag can not be broken, step on trap. Packaging Carton layer height can not be over two meters.
- 15.2.5 The transportation process should pay attention to the waterproof and moisture-proof measures. Product can not be watering. Ethylene sealed bags can not be unsealed.
- 15.2.6 Liquid crystals solidify under low temperature (below the storage temperature range) leading to defective orientation or the generation of air bubbles (black or white). Air bubbles may also be generated if the module is subject to a low temperature.
- 15.2.7 If the LCD modules have been operating for a long time showing the same display patterns, the display patterns may remain on screen as ghost images and a slight contrast irregularity may also appear. A normal operating status can be regained by suspending use for some time. It should be noted that this phenomenon does not adversely affect performance reliability.
- 15.2.8 To minimize the performance degradation of the LCD modules resulting from destruction caused by static electricity etc.,

15.3 Using LCD Modules

- 15.3.1 The hole in the printed circuit board is used to fix LCM. Attend to the following items when installing the LCM. Cover the surface with a transparent protective plate to protect the polarizer and LC cell.
- 15.3.2 When assembling the LCM into other equipment, the spacer to the bit between the LCM and the fitting plate should have enough height to avoid causing stress to the module surface, refer to the individual specifications for measurements. The measurement tolerance should be +/-0.1mm.

- 15.3.3 Precaution for assemble the module with BTB connector; Please note the position of the male and female connector position.
- 15.3.4 Precaution for soldering the LCM, Manual soldering temperature 300+/-20°C, time is 3~5S.
- 15.3.5 If soldering flux is used, be sure to remove any remaining flux after finishing to soldering operation (This does not apply in the case of a non-halogen type of flux). It is recommended that you protect the LCD surface with a cover during soldering to prevent any damage due to flux spatters.
- 15.3.6 When soldering the electroluminescent panel and PC board, the panel and board should not be detached more than three times. This maximum number is determined by the temperature and time conditions mentioned above, though there may be some variance depending on the temperature of the soldering iron.
- 15.3.7 When remove the electroluminescent panel from the PC board, be sure the solder has completely melted, the soldered pad on the PC board could be damaged.

15.4 Precautions for Operation

- 15.4.1 Viewing angle varies with the change of liquid crystal driving voltage (VLCD). Adjust VLCD to show the best contrast.
- 15.4.2 It is an indispensable condition to drive LCD within the specified voltage limit since the higher voltage then the limit cause the shorter LCD life. An electrochemical reaction due to direct current causes LCD undesirable deterioration, so that the use of direct current drive should be avoid.
- 15.4.3 Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD show dark color in them. However those phenomena do not mean malfunction or out of order with LCD which will come back in the specified operating temperature.
- 15.4.4 If the display area is pushed hard during operation, the display will become abnormal. However, it will return to normal if it is turned off and back on.
- 15.4.5 Slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit. Usage under the maximum operating temperature, 50%RH or less is required.
- 15.4.6 Input logic voltage before apply analog high voltage such as LCD driving voltage when power on.

 Remove analog high voltage before logic voltage when power off the module. Input each signal after the positive & negative voltage becomes stable.
- 15.4.7 Please keep the temperature within the specified range for use and storage. Polarization degradation, bubble generation or polarizer peel-off many occur with high temperature and high humidity.

15.5 Safety

- 15.5.1 It is recommended to crush damaged or unnecessary LCD into pieces and wash them off with solvents such as acetone and ethanol, which should later be burned.
- 15.5.2 If any liquid leaks out of a damaged glass cell and comes in contact with the hands, wash off thoroughly with soap and water.

15.6 Limited Warranty

- 15.6.1 Unless otherwise agreed between ODNA display and customer, ODNA display will replace or repair any of its LCD and LCM which ODNA display found to be defective electrically and visually when inspected in accordance with ODNA display quality standards, for a period of one year from date of shipment.
- 15.6.2 The warranty liability of ODNA display is limited to repair and/or replacement. ODNA display will not be responsible for any consequential loss.
- 15.6.3 If possible, we suggest you use up all modules in six months. If the module storage time over twelve months, we suggest that recheck it before the module be used.